



SANYO Semiconductors

DATA SHEET

LV5124T — CMOS IC 2-Cell Lithium-Ion Secondary Battery Protection IC

Overview

The LV5124T is a protection IC for 2-cell lithium-ion secondary batteries.

Features

- Monitoring function for each cell: Detects overcharge and over-discharge conditions and controls the charging and discharging operation of each cell.
- High detection voltage accuracy: Over-charge detection accuracy $\pm 25\text{mV}$
Over-discharge detection accuracy $\pm 100\text{mV}$
- Hysteresis cancel function: The hysteresis of over-discharge detection voltage is made small by sensing the connection of a load after overcharging has been detected.
- Discharge current monitoring function: Detects over-currents and load shorting, and an excessive discharge current is controlled.
- Latch function after detecting over-current (Release is made by connecting the charger)
- Low current consumption: Normal operation mode typ. $6.0\mu\text{A}$
Stand by mode max. $0.2\mu\text{A}$
- 0V cell charging function: Charging is enabled even when the cell voltage is 0V by giving a potential difference between the V_{DD} pin and V- pin.

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LV5124T

Specifications

Absolute Maximum Ratings at Ta = 25°C

Parameter	Symbol	Conditions	Ratings	Unit
Power supply voltage	V _{DD}		-0.3 to +12	V
Input voltage Charger minus voltage	V ⁻		V _{DD} -28 to V _{DD} +0.3	V
Output voltage	Cout pin voltage	V _{cout}	V _{DD} -28 to V _{DD} +0.3	V
	Dout pin voltage	V _{dout}	V _{SS} -0.3 to V _{DD} +0.3	V
Allowable power dissipation	P _{d max}	Independent IC	170	mW
Operating ambient temperature	T _{opr}		-30 to +85	°C
Storage temperature	T _{stg}		-40 to +125	°C

Electrical Characteristics at Ta = 25°C, unless especially specified.

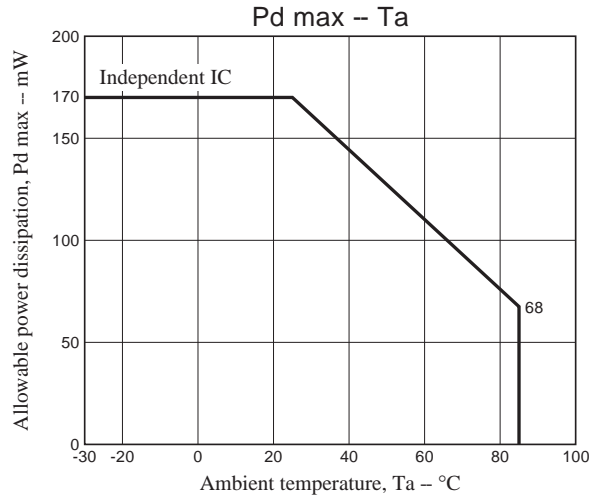
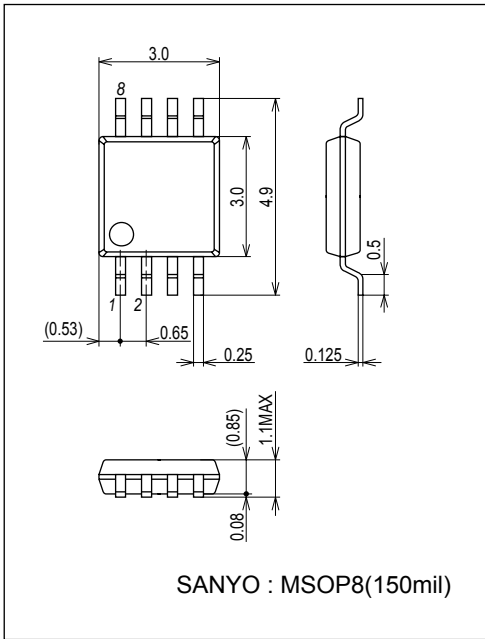
Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Operation input voltage	V _{cell}	Between V _{DD} and V _{SS}	1.5		10	V
0V cell charging minimum operation voltage	V _{min}	Between V _{DD} -V _{SS} =0 and V _{DD} -V ⁻			1.5	V
Over-charge detection voltage	V _{d1}		4.325	4.350	4.375	V
Over-charge release voltage	V _{r1}	V ⁻ ≤ V _{d3}	4.100	4.150	4.200	V
		V ⁻ > V _{d3}	4.250		4.360	V
Over-charge detection delay time	t _{d1}	V _{DD} -V _c =3.5V→4.5V, V _c -V _{SS} =3.5V	0.5	1.0	1.5	s
Over-charge release delay time	t _{r1}	V _{DD} -V _c =4.5V→3.5V, V _c -V _{SS} =3.5V	20.0	40.0	60.0	ms
Over-discharge detection voltage	V _{d2}		2.20	2.30	2.40	V
Over-discharge release hysteresis voltage	V _{h2}		10.0	20.0	40.0	mV
Over-discharge detection delay time	t _{d2}	V _{DD} -V _c =3.5V→2.2V, V _c -V _{SS} =3.5V	50	100	150	ms
Over-discharge release delay time	t _{r2}	V _{DD} -V _c =2.2V→3.5V, V _c -V _{SS} =3.5V	0.5	1.0	1.5	ms
Over-current detection voltage	V _{d3}	V _{DD} -V _c =3.5V, V _c -V _{SS} =3.5V	0.18	0.20	0.22	V
Over-current release hysteresis voltage	V _{h3}	V _{DD} -V _c =3.5V, V _c -V _{SS} =3.5V	5.0	10.0	20.0	mV
Over-current detection delay time	t _{d3}	V _{DD} -V _c =3.5V, V _c -V _{SS} =3.5V	2.5	5.0	7.5	ms
Over-current release delay time	t _{r3}	V _{DD} -V _c =3.5V, V _c -V _{SS} =3.5V	0.5	1.0	1.5	ms
Short circuit detection voltage	V _{d4}	V _{DD} -V _c =3.5V, V _c -V _{SS} =3.5V	1.0	1.3	1.6	V
Short circuit detection delay time	t _{d4}	V _{DD} -V _c =3.5V, V _c -V _{SS} =3.5V	0.2	0.5	0.8	ms
Standby release voltage	V _{stb}	V _{DD} -V _c =2.0V, V _c -V _{SS} =2.0V (V ⁻)-V _{SS}	V _{DD} ×0.4	V _{DD} ×0.5	V _{DD} ×0.6	V
Internal resistance (connect to V _{DD})	R _{DD}		100	200	400	kΩ
Internal resistance (connect to V _{SS})	R _{SS}		0.5	1.0	1.5	MΩ
Cout Nch ON voltage	V _{OL1}	I _{OL} =50μA, V _{DD} -V _c =4.4V, V _c -V _{SS} =4.4V			0.5	V
Cout Pch ON voltage	V _{OH1}	I _{OL} =50μA, V _{DD} -V _c =3.9V, V _c -V _{SS} =3.9V	V _{DD} -0.5			V
Dout Nch ON voltage	V _{OL2}	I _{OL} =50μA, V _{DD} -V _c =V _{d2} (min), V _c -V _{SS} =V _{d2} (min)			0.5	V
Dout Pch ON voltage	V _{OH2}	I _{OL} =50μA, V _{DD} -V _c =3.9V, V _c -V _{SS} =3.9V	V _{DD} -0.5			V
V _c input current	I _{vc}	V _{DD} -V _c =3.5V, V _c -V _{SS} =3.5V		0.0	1.0	μA
Current consumption	I _{DD}	V _{DD} -V _c =3.5V, V _c -V _{SS} =3.5V		6.0	13.0	μA
Standby current	I _{stb}	V _{DD} -V _c =2.2V, V _c -V _{SS} =3.5V			0.2	μA
T-terminal input ON voltage	V _{tst}	V _{DD} -V _c =3.5V, V _c -V _{SS} =3.5V	V _{DD} ×0.4	V _{DD} ×0.5	V _{DD} ×0.6	V

LV5124T

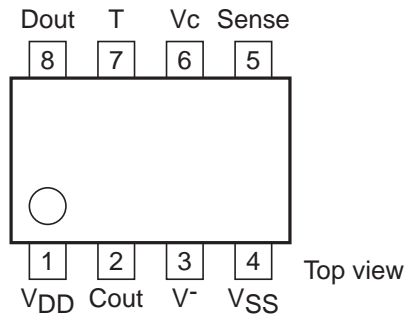
Package Dimensions

unit : mm (typ)

3245B



Pin Assignment

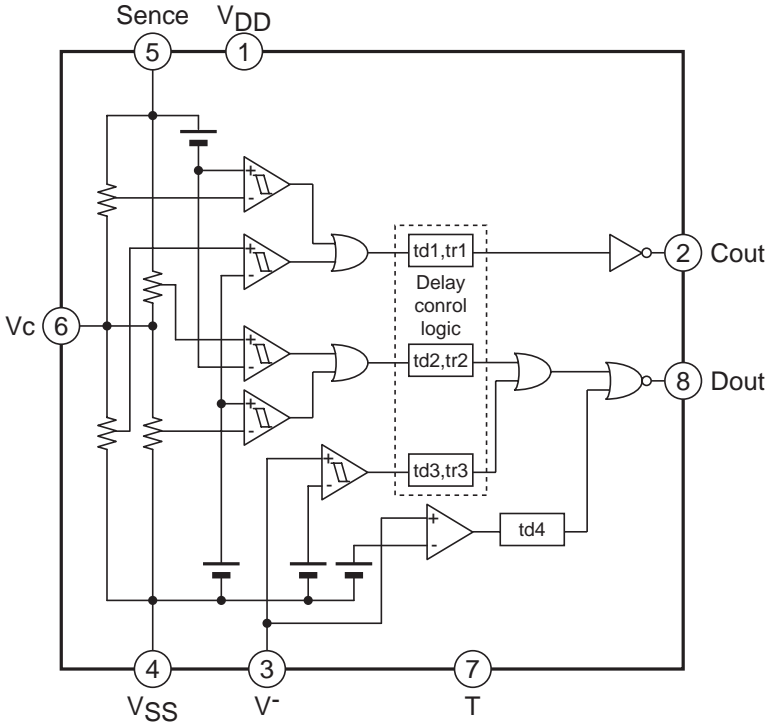


Pin Functions

Pin No.	Symbol	Description
1	VDD	VDD pin
2	Cout	Overcharge detection output pin
3	V-	Charger minus voltage input pin
4	VSS	VSS pin
5	Sense	Sense pin
6	Vc	Intermediate voltage input pin
7	T	Pin to shorten detection time("H": Shortening mode, "L": Normal mode)
8	Dout	Overdischarge detection output pin

LV5124T

Block Diagram



Functional Description

Over-charge detection

If either of the cell voltage is equal to or more than the over-charge detection voltage, stop further charging by turning “L” the Cout pin and turning off external Nch MOS FET after the over-charge detection delay time.

This delay time is set by the internal counter.

The over-charge detection comparator has the hysteresis function. Note that this hysteresis can be cancelled by connecting the load after detection of over-charge detection. and it becomes small to hysteresis peculiar to a comparator.

Once over-charge detection is made, over-current detection is not made to prevent incorrect operations. Note that short-circuit can be detected.

Over-charge release

If both cell voltages become equal to or less than the over-charge release voltage ($V_M \leq V_{d3}$) when charger is connected, or if it become equal to or less than the over-charge release voltage ($V_M > V_{d3}$) when load is connected, the Cout pin returns to “H” after the over-charge release delay time set by the internal counter.

When load is connected and either cell or both cell voltages are equal to or more than the over-charge release voltage ($V_M > V_{d3}$), the Cout pin does not return to “H”. But the load current flows through the parasitic diode of external Nch MOS FET on Cout, consequently each cell voltage becomes equal to or less than over-charge release voltage ($V_M > V_{d3}$), the Cout pin returns to “H” after the over-charge release delay time.

Over-discharge detection

When either cell voltage is equal to or less than over-discharge voltage, the IC stops further discharging by turning the Dout pin “L” and turning off external Nch MOS FET after the over-charge detection delay time.

The IC goes into stand-by mode after detecting over-discharge and its consumption current is kept at about 0A. After over-discharge detection, the V- pin will be connected to V_{DD} pin via internal resistor (typ 200k Ω).

Over-discharge release

Release from over-discharge is made by only connecting charger. If the V- pin voltage becomes equal to or lower than the stand-by release voltage by connecting charger after detecting over-discharge, The IC is released from the stand-by state to start cell voltage monitoring. If both cell voltages become equal to or more than the over-discharge detection voltage by charging, the Dout pin returns to “H” after the over-discharge release delay time set by the internal counter.

Over-current detection

When excessive current flows through the battery, the V- pin voltage rises by the ON resistor of external MOS FET and becomes equal to or more than the over-current detection voltage, the Dout pin turns to “L” after the over-current detection delay time and the external Nch MOS FET is turned off to prevent excessive current in the circuit. The detection delay time is set by the internal counter. After detection, the V- pin will be connected to V_{SS} via internal resistor (typ 1M Ω). It will not go into stand-by mode after detecting over-current.

Short circuit detection

If greater discharging current flows through the battery and the V- pin voltage becomes equal to or more than the short-circuit detection voltage, it will go into short-circuit detection state after the short circuit delay time shorter than the over-current detection delay time. When short-circuit is detected, just like the time of over-current detection, the Dout pin turns to “L” and external Nch MOS FET is turned off to prevent high current in the circuit. The V- pin will be connected to V_{SS} after detection via internal resistor (typ 1M Ω). It will not go into stand-by mode after detecting short circuit.

Over-current/short-detection release

After detecting over-current or short circuit, the internal resistor (typ.1M Ω) between V- pin and V_{SS} pin becomes effective. In this case, the V-pin voltage will be more than over-current detection voltage because of the relation between internal resistor and the internal impedance of V- pin. Therefore, if the load resistor is removed after detecting over-current or short circuit, the detection state will be kept. Release from over-current or short circuit is only made by connecting a charger to make the V- pins lower than over-current detection voltage and the Dout pin returns to “H” after over-current release delay time set by the internal counter.

0V cell charging operation

If voltage between V_{DD} and V becomes equal to or more than the 0V cell charging lowest operation voltage when the cell voltage is 0V, the Cout pin turns to “H” and charging is enabled.

Shorten the test time

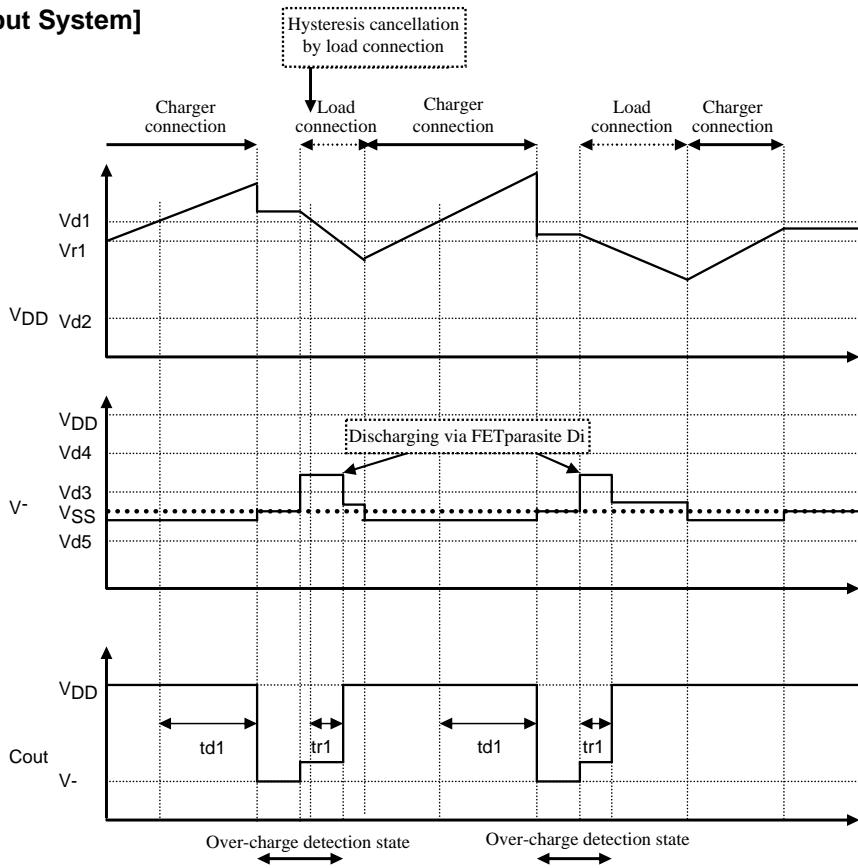
By turning T pin to the V_{DD} , the delay times set by the internal counter can be cut. If T pin is open, the delay times are normal. Delay time not set by the counter just like as short circuit detection delay cannot be controlled by this pin. And we recommend that T pin is connected to V_{SS} to prevent malfunction when excessive current flows in short circuit operation.

Operation in case of detection overlap

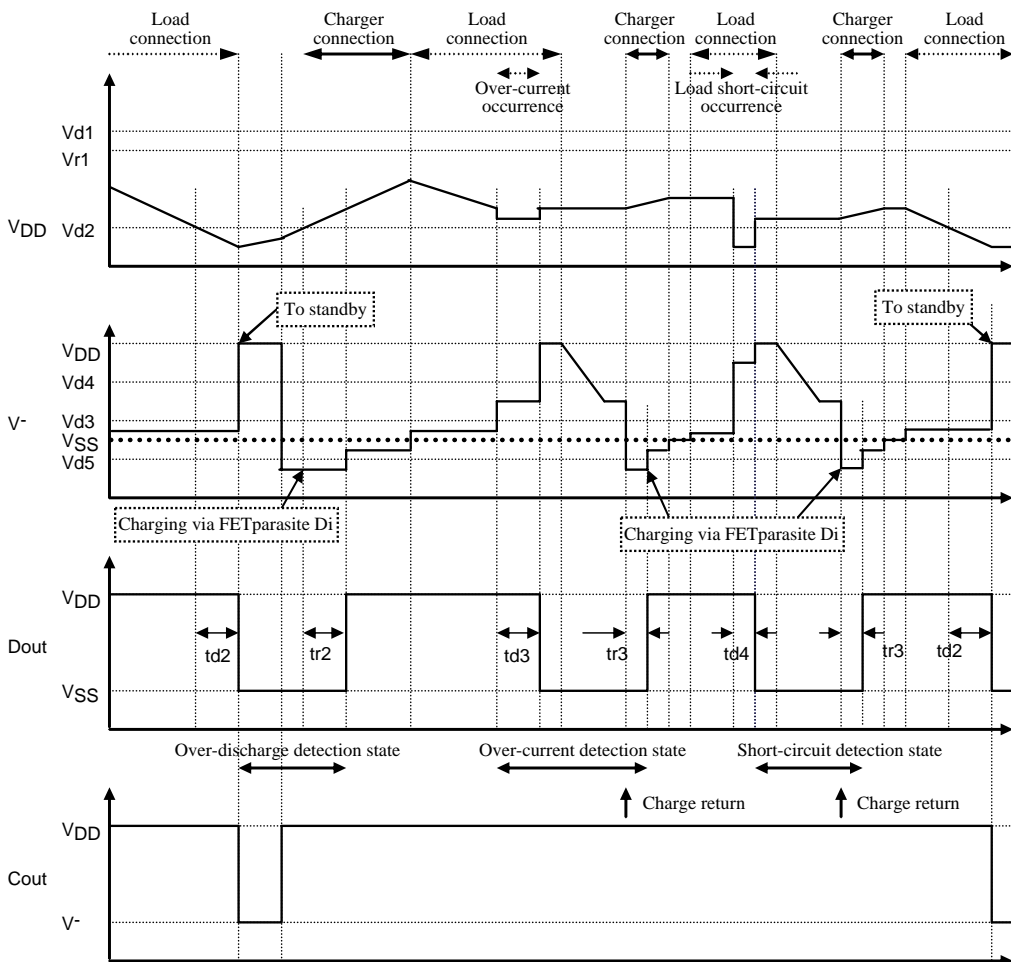
Overlap state		Operation in case of detection overlap	State after detection
During over-charge detection,	Over-discharge detection is made,	Over-charge detection is prioritized. If over-discharge state continues even after over-charge detection, over-discharge detection is resumed.	When over-charge state is made first, V- is released. When over-discharge is detected after over-charge state is made, the IC does not go into the stand-by mode. Note that V- is connected to V_{DD} via 200k Ω .
	Over-current detection is made,	(*1) Both detections can be made in parallel. Over-charge detection continues even when the over-current state is made first. If the over-charge state is made first, over-current detection is interrupted.	(*2) When over-current state is made first, V- is connected to V_{SS} via 1M Ω . When over-charge state is made first, V- is released.
During over-discharge detection,	Over-charge detection is made,	Over-discharge detection is interrupted and over-charge detection is prioritized. When over-discharge state continues even after over-charge state is made, over-discharge detection is resumed.	The IC does not go into the stand-by mode when over-discharge state is made after over-charge detection. Note that V- is connected to V_{DD} via 200k Ω .
	Over-current detection is made,	(*3) Both detections can be made in parallel. Over-discharge detection continues even when the over-current state is made first. But over-current detection is interrupted when the over-discharge state is made first,	(*4) If over-current state is made first, V- will be connected to V_{SS} via 1M Ω . If over-discharge detection is made next, V- also will be connected to V_{DD} via 200k Ω to get into stand-by mode. If over-discharge state is made first, V- will be connected to V_{DD} via 200k Ω to get into stand-by mode.
During over-current detection,	Over-charge detection is made,	(*1)	(*2)
	Over-discharge detection is made,	(*3)	(*4)

(Note) Short-circuit detection can be made independently.

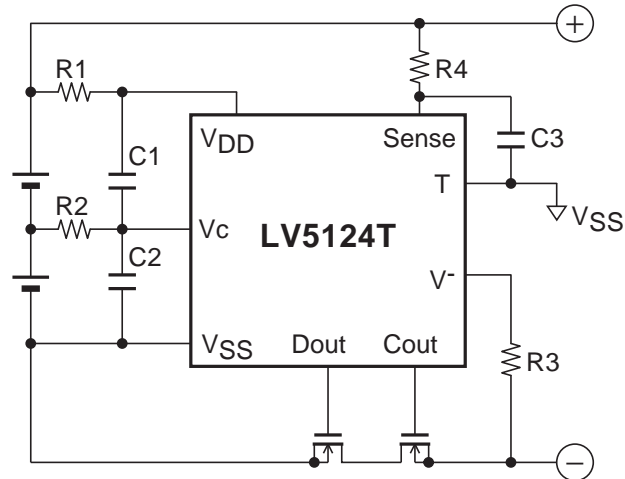
Timing Chart
[Cout Output System]



[Dout Output System]



Application Circuit Example



Components	Recommended value	max	unit
R1, R2	100	1k	Ω
R3	2k	4k	Ω
R4	100	10k	Ω
C1, C2, C3	0.1 μ	1 μ	F

* These numbers don't mean to guarantee the characteristic of the IC.

* In addition to the components in the upper diagram, it is necessary to insert a capacitor with enough capacity between VDD and VSS of the IC as near as possible to stabilize the power supply voltage to the IC.

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